

Electrical Specifications ($T_A=+25^\circ\text{C}$)

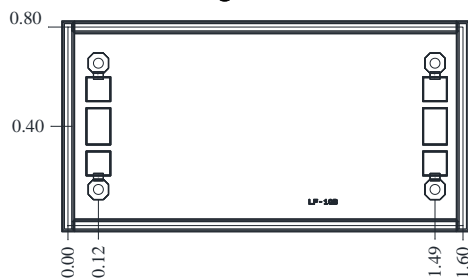
Parameter	Min.	Typ.	Max.	Unit
Cut-off Freq. (f_0)	-	2	-	GHz
Pass band	2	-	21	GHz
Insertion Loss @ f_0	-	-	2	dB
Return Loss	15	-	-	dB
Out of band Attenuation	$\geq 20@1.45\text{GHz}$			dB
	$\geq 40@1.35\text{GHz}$			dB

Max. Input Power: 30dBm

Operating Temperature: $-55^\circ\text{C} \sim +125^\circ\text{C}$

Storage Temperature: $-65^\circ\text{C} \sim +150^\circ\text{C}$

Outline Drawing



Notes:

1. Dimensions are in millimeters. Tolerance: ± 0.05 mm
2. Die thickness is 0.1 mm
3. Typical bond pad size is 0.1 x 0.1 mm

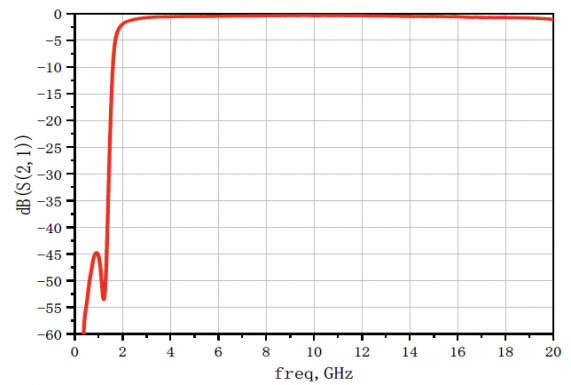
Recommended Assembly Diagram



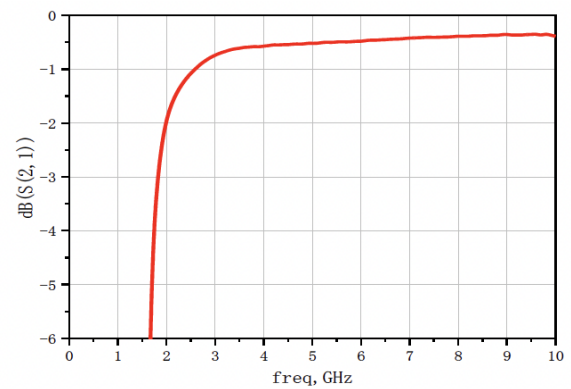
Notes:

1. Die is back-metallized and can be mounted with AuSn eutectic preform or with electrically conductive epoxy.
2. We recommend using $\Phi 25\mu\text{m}$ Au wire for wire-bonding, with max wire length of 400 μm .
3. Sinter using AuSn (80/20) alloy, ensuring the temperature does not exceed 300°C for a maximum of 30 seconds.
4. Handle die in clean environment. Do not attempt to clean the chip using liquid cleaning systems.
5. Die is ESD sensitive. ESD protection is required during usage and storage.

Typical Wideband Insertion Loss at $T_A=25$



Typical Insertion Loss at $T_A=25$



Typical Return Loss at $T_A=25$

